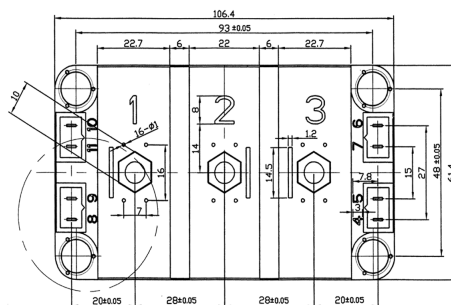
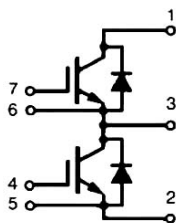
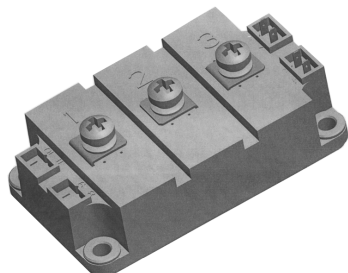


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NPT IGBT Modules

Dimensions in mm (1mm = 0.0394")



Absolute Maximum Ratings

$T_c = 25^\circ\text{C}$, unless otherwise specified

Symbol	Conditions	Values	Units
V_{CES}		1200	V
I_c	$T_c = 25(80)^\circ\text{C}$	210(150)	A
I_{CRM}	$T_c = 25(80)^\circ\text{C}$, $t_p = 1\text{ms}$	420(300)	A
V_{GES}		± 20	V
P_{tot}		1250	W
$T_{Vj}(T_{stg})$	$T_{OPERATION} \leq T_{stg}$	$-40 \dots +125(150)$	$^\circ\text{C}$
V_{isol}	AC, 1min	2500	V
R_{thJC}		≤ 0.1	K/W
R_{thJCD}		≤ 0.25	

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NPT IGBT Modules

Electrical Characteristics

T_c = 25°C, unless otherwise specified

Symbol	Conditions	min.	typ.	max.	Units
Static Characteristics					
V _{GE(th)}	V _{GE} = V _{CE} , I _C = 6mA	4.5	5.5	6.5	V
I _{GES}	V _{GE} = 0; V _{CE} = 1200V; T _j = 25(125)°C		2(8)	2.8	mA
I _{GES}	V _{GE} = 20V, V _{CE} = 0			320	nA
V _{CE(sat)}	I _C = 150A; V _{GE} = 15V; T _j = 25(125)°C; chip level		2.5(3.1)	3(3.7)	V
AC Characteristics					
C _{ies}	under following conditions		11		nF
C _{oes}	V _{GE} = 0, V _{CE} = 25V, f = 1MHz		1.6		
C _{res}			0.6		
g _{fs}	V _{CE} = 20V, I _C = 150A	62			S
Switching Characteristics					
t _{d(on)}	V _{CC} = 600V, I _C = 150A		200	400	ns
t _r	R _{Gon} = R _{Goff} = 5.6Ω, T _j = 125°C		100	200	
t _{d(off)}	V _{GE} = ± 15V		600	800	
t _f			70	100	
FWD under following conditions:					
V _F	I _F = 150A, V _{GE} = 0V, T _j = 25(125)°C		2.3(1.8)	2.8	V
t _{rr}	I _F = 150A, V _R = -600V, V _{GE} = 0V, di/dt = -1500A/us, T _j = 125°C		0.4		us
Q _{rr}	I _F = 150A, V _{GE} = 0V, V _R = -600V di/dt = -1500A/us, T _j = 25(125)°C		5(18)		uC
Mechanical Data					
M _s	to heatsink M6	3		5	Nm
M _t	to terminals M5	2.5		5	Nm
w				325	g

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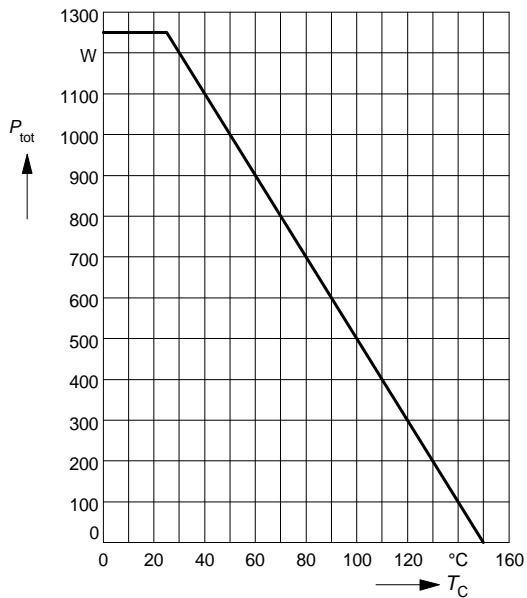
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NPT IGBT Modules

Power dissipation

$$P_{\text{tot}} = f(T_C)$$

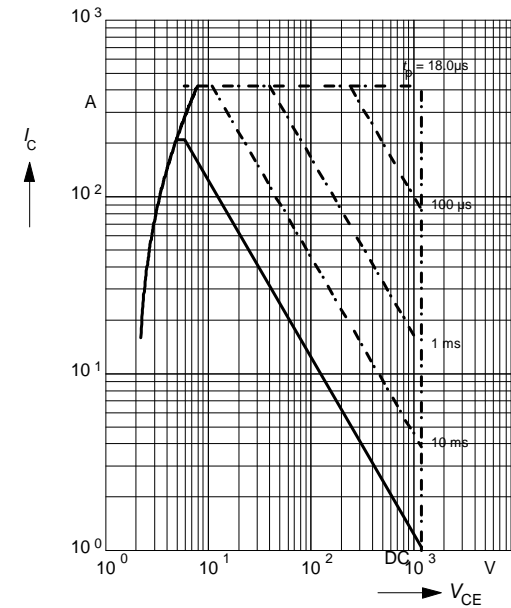
parameter: $T_j \leq 150^\circ\text{C}$



Safe operating area

$$I_C = f(V_{CE})$$

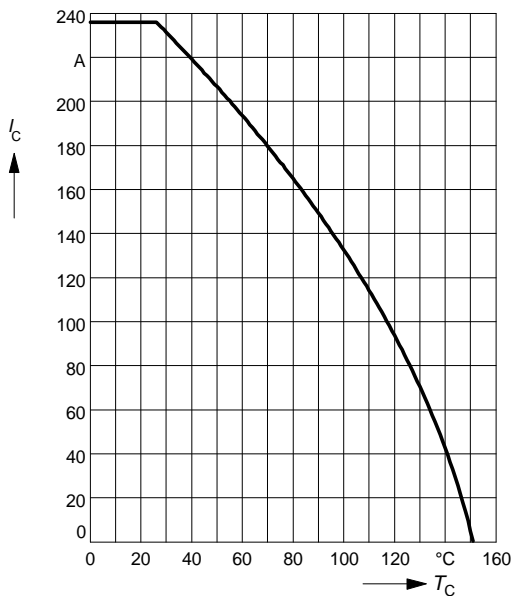
parameter: $D = 0$, $T_C = 25^\circ\text{C}$, $T_j \leq 150^\circ\text{C}$



Collector current

$$I_C = f(T_C)$$

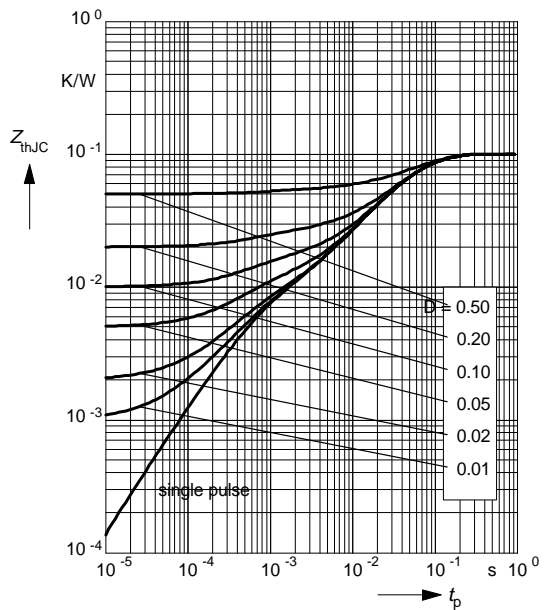
parameter: $V_{GE} \geq 15\text{ V}$, $T_j \leq 150^\circ\text{C}$



Transient thermal impedance IGBT

$$Z_{\text{thJC}} = f(t_p)$$

parameter: $D = t_p / T$



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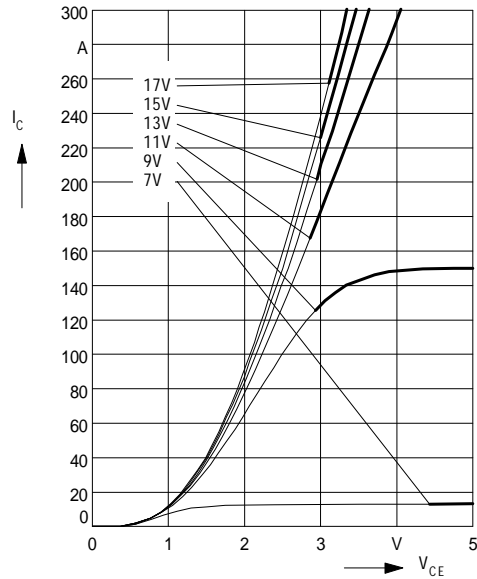
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NPT IGBT Modules

Typ. output characteristics

$$I_C = f(V_{CE})$$

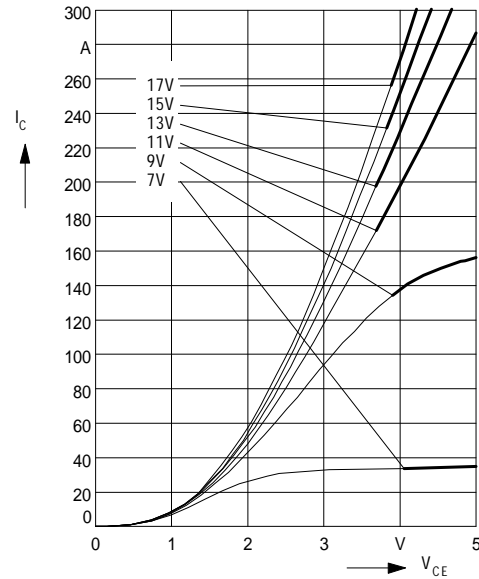
parameter: $t_p = 80 \mu s$, $T_j = 25^\circ C$



Typ. output characteristics

$$I_C = f(V_{CE})$$

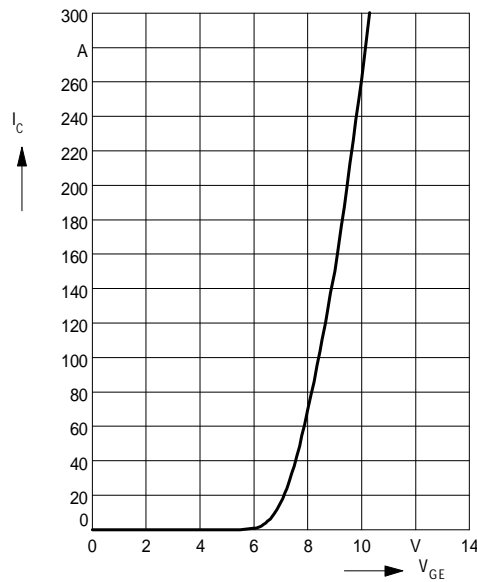
parameter: $t_p = 80 \mu s$, $T_j = 125^\circ C$



Typ. transfer characteristics

$$I_C = f(V_{GE})$$

parameter: $t_p = 80 \mu s$, $V_{CE} = 20 V$



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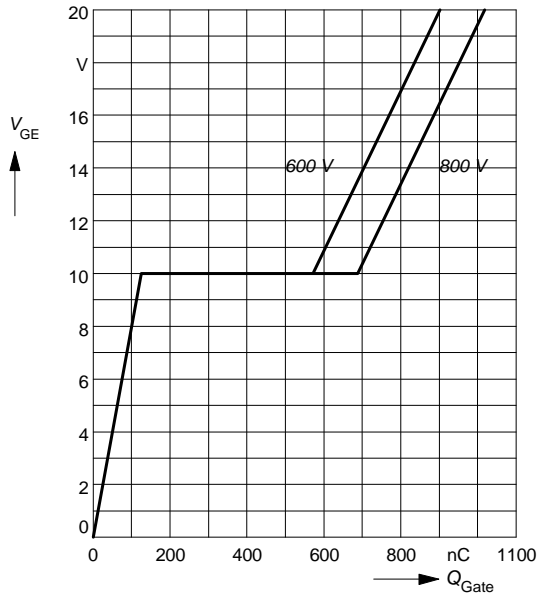
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NPT IGBT Modules

Typ. gate charge

$$V_{GE} = f(Q_{Gate})$$

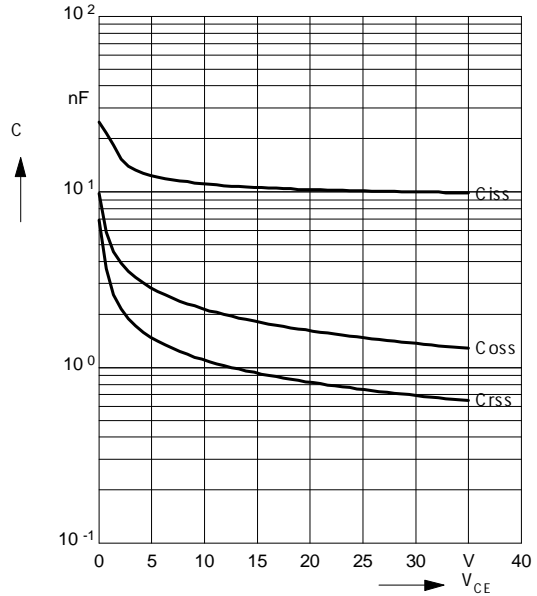
parameter: $I_{C\ puls} = 150\ A$



Typ. capacitances

$$C = f(V_{CE})$$

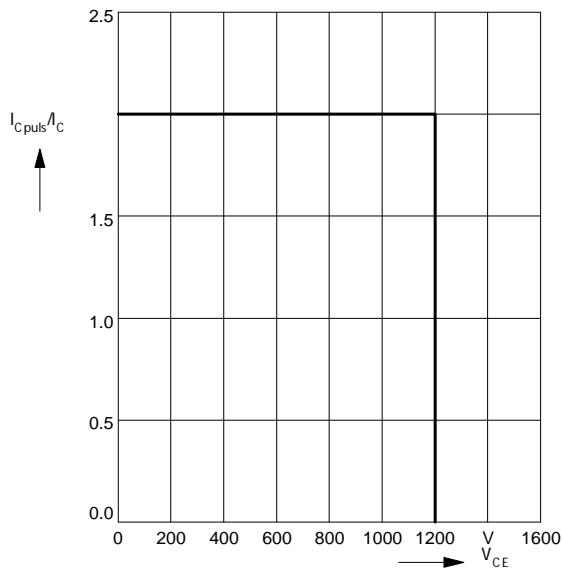
parameter: $V_{GE} = 0\ V, f = 1\ MHz$



Reverse biased safe operating area

$$I_{C\ puls} = f(V_{CE}), T_j = 150^\circ C$$

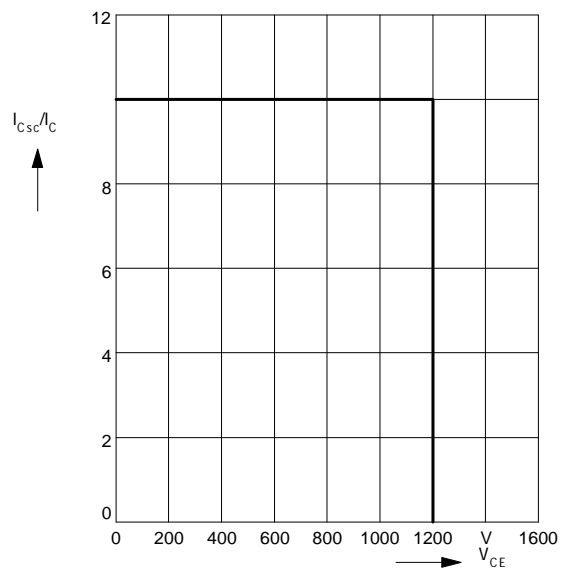
parameter: $V_{GE} = 15\ V$



Short circuit safe operating area

$$I_{C\ sc} = f(V_{CE}), T_j = 150^\circ C$$

parameter: $V_{GE} = \pm 15\ V, t_{sc} \leq 10\ \mu s, L < 25\ nH$



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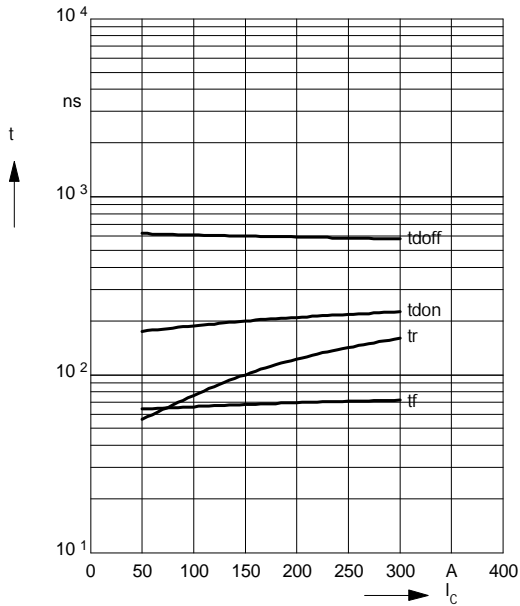
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NPT IGBT Modules

Typ. switching time

$t = f(I_C)$, inductive load, $T_j = 125^\circ\text{C}$

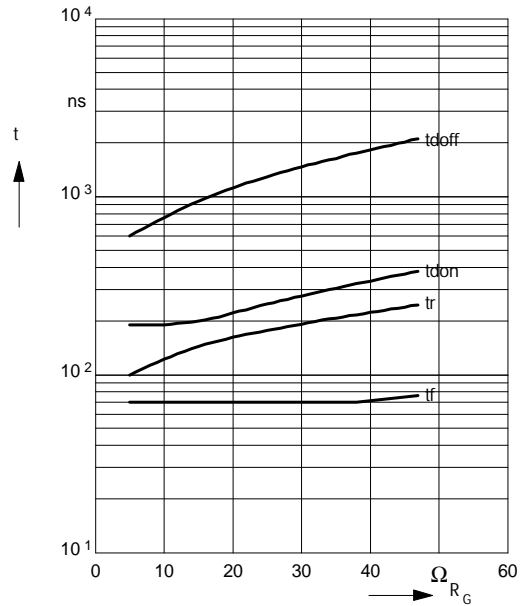
par.: $V_{CE} = 600\text{ V}$, $V_{GE} = \pm 15\text{ V}$, $R_G = 5.6\ \Omega$



Typ. switching time

$t = f(R_G)$, inductive load, $T_j = 125^\circ\text{C}$

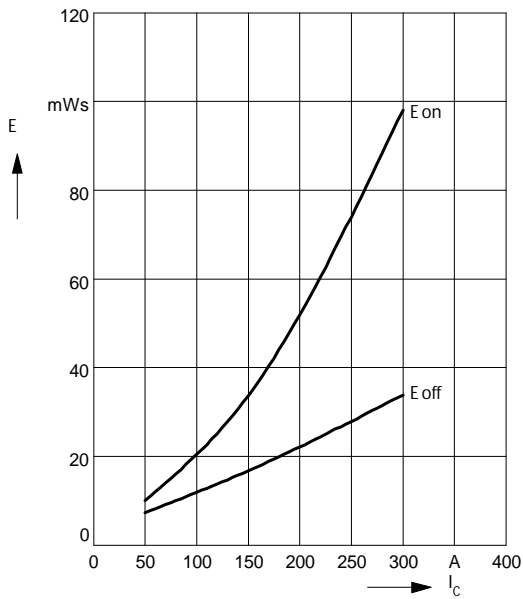
par.: $V_{CE} = 600\text{ V}$, $V_{GE} = \pm 15\text{ V}$, $I_C = 150\text{ A}$



Typ. switching losses

$E = f(I_C)$, inductive load, $T_j = 125^\circ\text{C}$

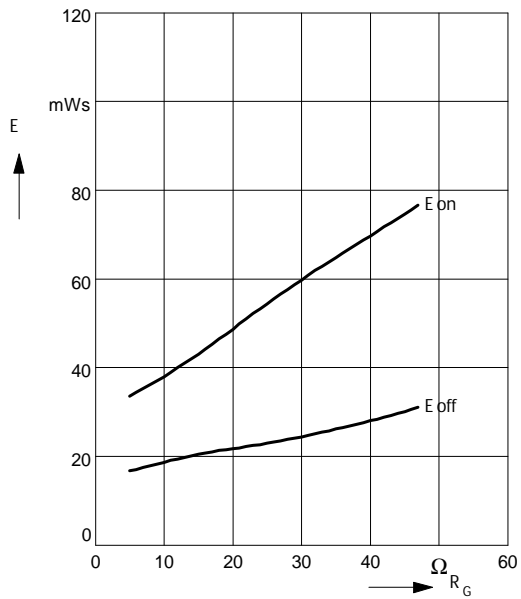
par.: $V_{CE} = 600\text{ V}$, $V_{GE} = \pm 15\text{ V}$, $R_G = 5.6\ \Omega$



Typ. switching losses

$E = f(R_G)$, inductive load, $T_j = 125^\circ\text{C}$

par.: $V_{CE} = 600\text{ V}$, $V_{GE} = \pm 15\text{ V}$, $I_C = 150\text{ A}$

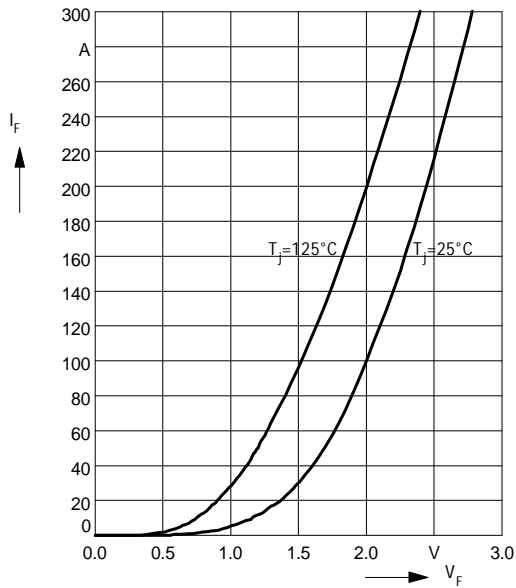


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NPT IGBT Modules

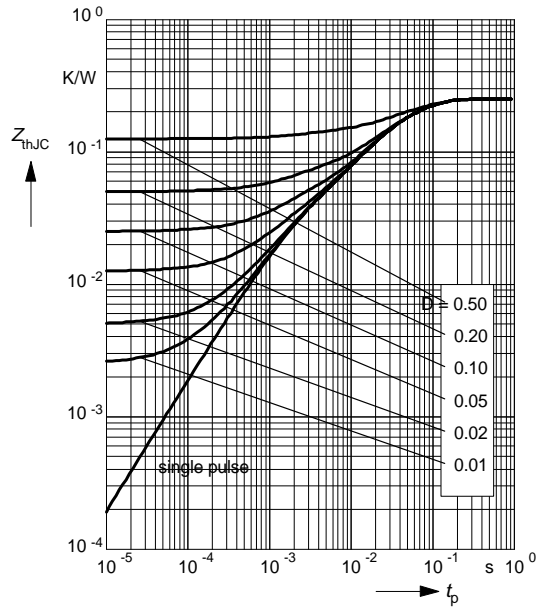
Forward characteristics of fast recovery
reverse diode $I_F = f(V_F)$
parameter: T_j



Transient thermal impedance Diode

$$Z_{th\,JC} = f(t_p)$$

parameter: $D = t_p / T$



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